



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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08 216 FR4 70 L20.70 P10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

08\_216\_FR4\_70\_L20.70\_p10

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	70 $\mu$	Copper		A1
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-2	70 $\mu$	Copper		A2
	200 $\mu$	L-FR4		
Layer-3	70 $\mu$	Copper		A3
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-4	70 $\mu$	Copper		A2
	200 $\mu$	L-FR4		
Layer-5	70 $\mu$	Copper		A3
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-6	70 $\mu$	Copper		A3
	200 $\mu$	L-FR4		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-7	70 $\mu$	Copper		A3
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
Layer-99	70 $\mu$	Copper		

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